1. General description

The HEF4069UB is a general purpose hex unbuffered inverter. Each inverter has a single stage.

It operates over a recommended V_{DD} power supply range of 3 V to 15 V referenced to V_{SS} (usually ground). Unused inputs must be connected to V_{DD} , V_{SS} , or another input.

2. Features and benefits

- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Specified from -40 °C to +85 °C and -40 °C to +125 °C
- Complies with JEDEC standard JESD 13-B

3. Applications

Oscillator

4. Ordering information

Table 1.Ordering information

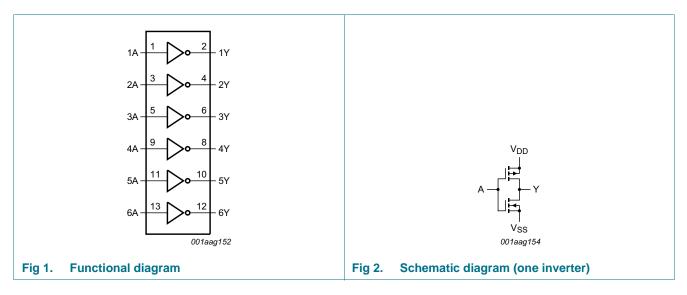
All types operate from -40 °C to +125 °C.

Type number	Package				
	Name	Description	Version		
HEF4069UBT	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1		
HEF4069UBTT	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1		



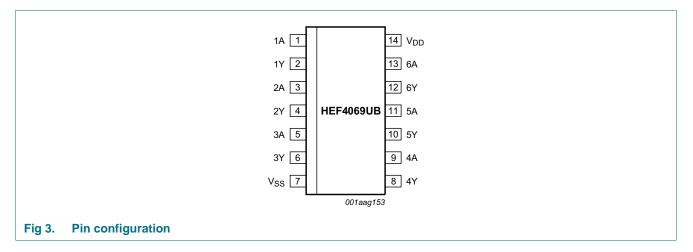
Hex unbuffered inverter

5. Functional diagram



6. Pinning information

6.1 Pinning



6.2 Pin description

Table 2. Pin description		
Symbol	Pin	Description
1A to 6A	1, 3, 5, 9, 11, 13	input
1Y to 6Y	2, 4, 6, 8, 10, 12	output
V _{SS}	7	ground (0 V)
V _{DD}	14	supply voltage

Hex unbuffered inverter

7. Limiting values

Table 3. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V _{DD}	supply voltage			-0.5	+18	V
I _{IK}	input clamping current	$V_{I} < -0.5$ V or $V_{I} > V_{DD}$ + 0.5 V		-	±10	mA
VI	input voltage			-0.5	V _{DD} + 0.5	V
I _{OK}	output clamping current	V_{O} < -0.5 V or V_{O} > V_{DD} + 0.5 V		-	±10	mA
I _{I/O}	input/output current			-	±10	mA
I _{DD}	supply current			-	50	mA
T _{stg}	storage temperature			-65	+150	°C
T _{amb}	ambient temperature			-40	+125	°C
P _{tot}	total power dissipation	$T_{amb} = -40 \ ^{\circ}C$ to +125 $^{\circ}C$				
		SO14	<u>[1]</u>	-	500	mW
		TSSOP14	[2]	-	500	mW
Р	power dissipation	per output		-	100	mW

[1] For SO14 packages: above T_{amb} = 70 °C, P_{tot} derates linearly with 8 mW/K.

[2] For TSSOP14 packages: above T_{amb} = 60 °C, P_{tot} derates linearly with 5.5 mW/K.

8. Recommended operating conditions

Table 4. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{DD}	supply voltage		3	-	15	V
VI	input voltage		0	-	V_{DD}	V
T _{amb}	ambient temperature	in free air	-40	-	+125	°C

9. Static characteristics

Table 5. Static characteristics

 $V_{SS} = 0$ V; $V_{I} = V_{SS}$ or V_{DD} ; unless otherwise specified.

Symbol	Parameter	Conditions	V _{DD}	T _{amb} = -40 °C		T _{amb} = +25 °C		T _{amb} = +85 °C		T _{amb} = +125 °C		Unit
				Min	Max	Min	Max	Min	Max	Min	Max	
VIH	HIGH-level	I _O < 1 μA	5 V	4	-	4	-	4	-	4	-	V
	input voltage		10 V	8	-	8	-	8	-	8	-	V
			15 V	12.5	-	12.5	-	12.5	-	12.5	-	V
VIL	LOW-level	I _O < 1 μA	5 V	-	1	-	1	-	1	-	1	V
	input voltage		10 V	-	2	-	2	-	2	-	2	V
			15 V	-	2.5	-	2.5	-	2.5	-	2.5	V
V _{OH}	HIGH-level	I _O < 1 μA	5 V	4.95	-	4.95	-	4.95	-	4.95	-	V
	output voltage		10 V	9.95	-	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	14.95	-	V
V _{OL}	LOW-level	I _O < 1 μA	5 V	-	0.05	-	0.05	-	0.05	-	0.05	V
	output voltage	e	10 V	-	0.05	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	-	0.05	V
I _{OH}	HIGH-level	V _O = 2.5 V	5 V	-	-1.7	-	-1.4	-	-1.1	-	-1.1	mA
	output current	put current $V_0 = 4.6 V$	5 V	-	-0.64	-	-0.5	-	-0.36	-	-0.36	mA
		V _O = 9.5 V	10 V	-	-1.6	-	-1.3	-	-0.9	-	-0.9	mA
		V _O = 13.5 V	15 V	-	-4.2	-	-3.4	-	-2.4	-	-2.4	mA
I _{OL}	LOW-level	$V_{O} = 0.4 V$	5 V	0.64	-	0.5	-	0.36	-	0.36	-	mA
	output current	$V_{O} = 0.5 V$	10 V	1.6	-	1.3	-	0.9	-	0.9	-	mA
		V _O = 1.5 V	15 V	4.2	-	3.4	-	2.4	-	2.4	-	mA
I	input leakage current		15 V	-	±0.1	-	±0.1	-	±1.0	-	±1.0	μΑ
I _{DD}	supply current		5 V	-	0.25	-	0.25	-	7.5	-	7.5	μA
		combinations;	10 V	-	0.5	-	0.5	-	15.0	-	15.0	μA
		I _O = 0 A	15 V	-	1.0	-	1.0	-	30.0	-	30.0	μA
CI	input capacitance	digital inputs		-	-	-	7.5	-	-	-	-	pF

Hex unbuffered inverter

10. Dynamic characteristics

Table 6. Dynamic characteristics

 $T_{amb} = 25 \ ^{\circ}C$; for waveforms see <u>Figure 4</u>; for test circuit see <u>Figure 5</u>.

Symbol	Parameter	Conditions	V _{DD}	Extrapolation formula ^[1]	Min	Тур	Max	Unit
t _{PHL}	HIGH to LOW	nA to nY;	5 V	18 ns + (0.55 ns/pF)C _L	-	45	90	ns
	propagation delay		10 V	9 ns + (0.23 ns/pF)C _L	-	20	40	ns
			15 V	7 ns + (0.16 ns/pF)C _L	-	15	25	ns
t _{PLH}	LOW to HIGH	nA to nY	5 V	13 ns + (0.55 ns/pF)C _L	-	40	80	ns
propagation delay	propagation delay		10 V	9 ns + (0.23 ns/pF)C _L	-	20	40	ns
		15 V	7 ns + (0.16 ns/pF)C _L	-	15	30	ns	
t _{THL} H	HIGH to LOW output	output nY	5 V	10 ns + (1.00 ns/pF)C _L	-	60	120	ns
	transition time		10 V	9 ns + (0.42 ns/pF)C _L	-	30	60	ns
			15 V	6 ns + (0.28 ns/pF)C _L	-	20	40	ns
t _{TLH}	LOW to HIGH output	out output nY	5 V	10 ns + (1.00 ns/pF)C _L	-	60	120	ns
	transition time		10 V	9 ns + (0.42 ns/pF)C _L	-	30	60	ns
			15 V	6 ns + (0.28 ns/pF)C _L	-	20	40	ns

[1] The typical value of the propagation delay and output transition time can be calculated with the extrapolation formula (C_L in pF).

Table 7. Dynamic power dissipation

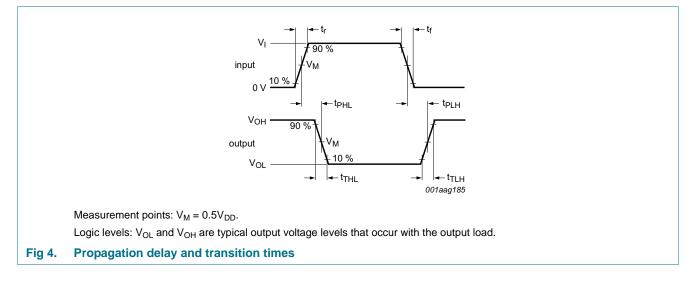
 $V_{SS} = 0 V; t_r = t_f \le 20 ns; T_{amb} = 25 \ ^{\circ}C.$

Symbol	Parameter	V _{DD}	Typical formula	Where
PD	dynamic power dissipation	5 V	$P_D = 600 \times f_i + \Sigma(f_o \times C_L) \times V_DD^2 \; (\muW)$	$f_i = input frequency in MHz;$
		10 V	$P_D = 4000 \times f_i + \Sigma(f_o \times C_L) \times V_DD^2 \; (\muW)$	$f_o = output frequency in MHz;$
		15 V	$P_{D} = 22000 \times f_{i} + \Sigma(f_{o} \times C_{L}) \times V_{DD}^2 \ (\muW)$	C_L = output load capacitance in pF;
				$\Sigma(f_o \times C_L)$ = sum of the outputs;
				V_{DD} = supply voltage in V.



Hex unbuffered inverter

11. Waveforms



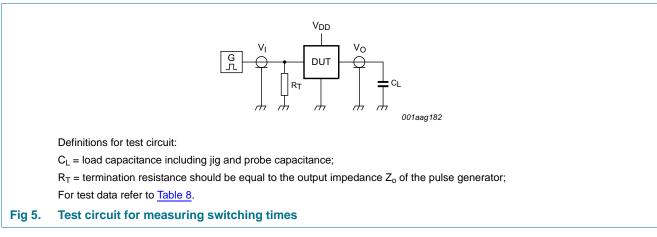
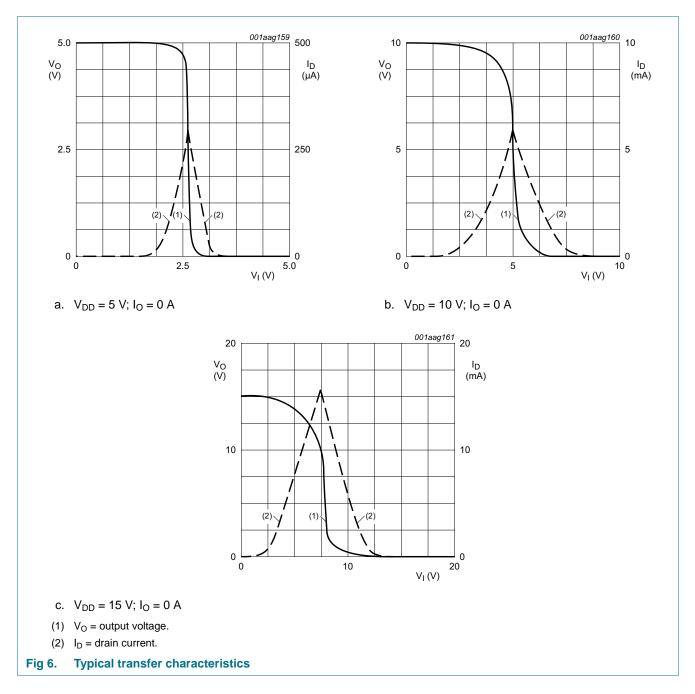


Table 8. Test data

Supply voltage	Input	Load	
V _{DD}	VI	t _r , t _f	CL
5 V to 15 V	V _{SS} or V _{DD}	≤ 20 ns	50 pF

Hex unbuffered inverter



11.1 Transfer characteristics

HEF4069UB Product data sheet

12. Application information

Some examples of applications for the HEF4069UB.

<u>Figure 7</u> shows an astable relaxation oscillator using two HEF4069UB inverters and 2 BAW62 diodes. The oscillation frequency is mainly determined by R1 × C1, provided R1 << R2 and R2 × C2 << R1 × C1.

The function of R2 is to minimize the influence of the forward voltage across the protection diodes on the frequency; C2 is a stray (parasitic) capacitance.

The period T_p is given by $T_p = T_1 + T_2$,

where:

$$T_1 = RICIIn \frac{V_{DD} + V_{ST}}{V_{ST}}$$

$$T_2 = RICIIn \frac{2V_{DD} - V_{ST}}{V_{DD} - V_{ST}}$$

 V_{ST} = the signal threshold level of the inverter.

The period is fairly independent of $V_{\text{DD}},\,V_{\text{ST}}$ and temperature. The duty factor, however, is influenced by $V_{\text{ST}}.$

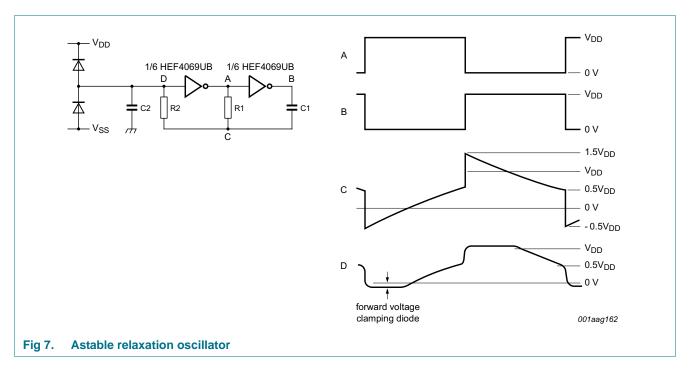


Figure 8 shows a crystal oscillator for frequencies up to 10 MHz using two HEF4069UB inverters. The second inverter amplifies the oscillator output voltage to a level sufficient to drive other Local Oxidation CMOS (LOCMOS) circuits.

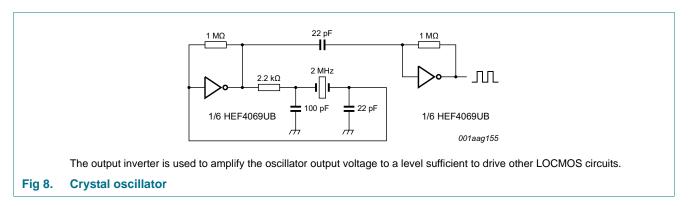
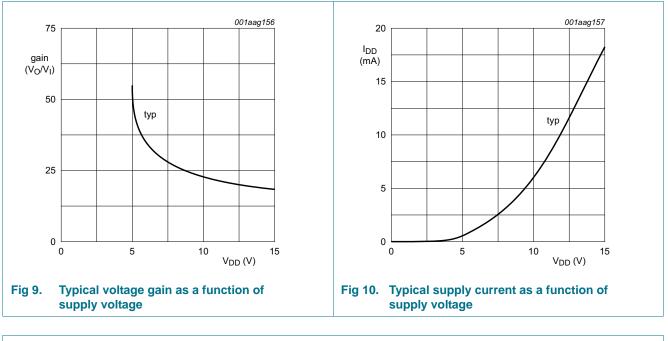
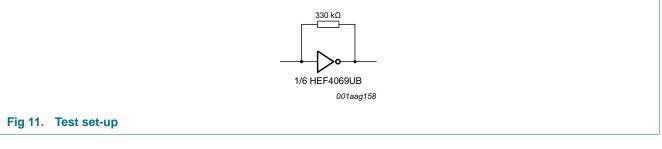


Figure 9 and Figure 10 show voltage gain and supply current. Figure 11 shows the test set-up and an example of an analog amplifier using one HEF4069UB.





HEF4069UB **Product data sheet**

Hex unbuffered inverter

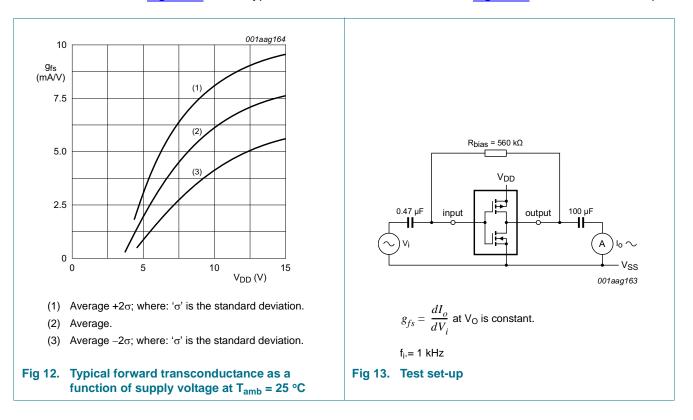


Figure 12 shows typical forward transconductance and Figure 13 shows the test set-up.

Hex unbuffered inverter

13. Package outline

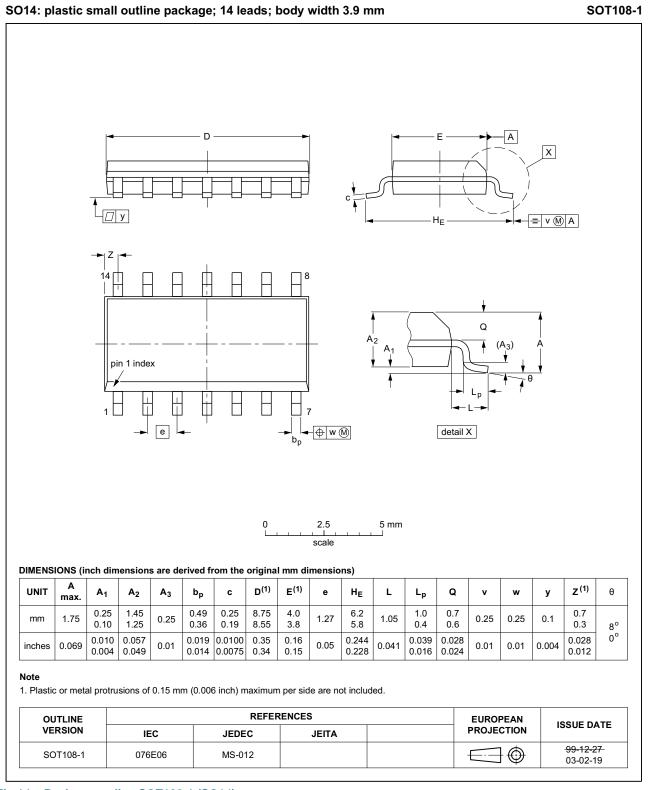


Fig 14. Package outline SOT108-1 (SO14)

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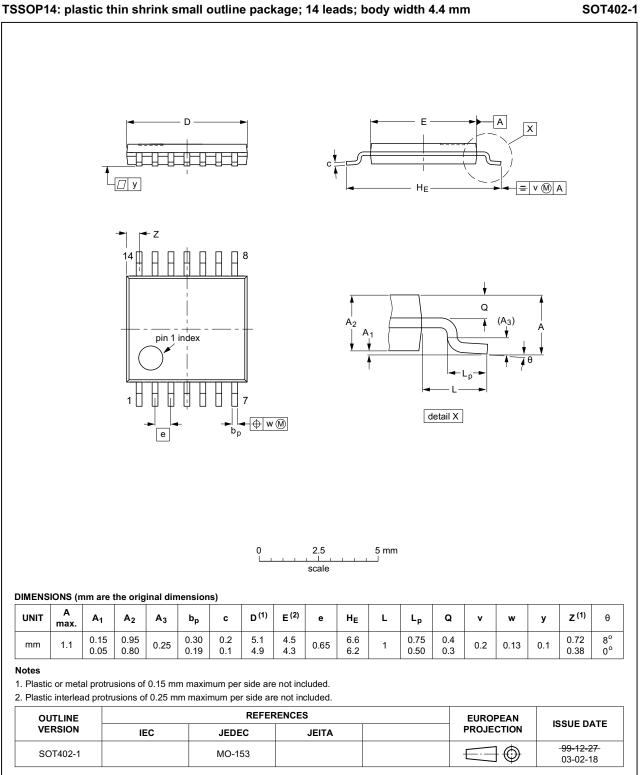


Fig 15. Package outline SOT402-1 (TSSOP14)

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14. Abbreviations

Table 9. Abbreviations		
Acronym	Description	
DUT	Device Under Test	

15. Revision history

Table 10.Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4069UB v.9	20151216	Product data sheet	-	HEF4069UB v.8
Modifications:	Type number	HEF4069UBP (SOT27-1) rem	oved.	·
HEF4069UB v.8	20111116	Product data sheet	-	HEF4069UB v.7
Modifications:	 Legal pages u 	updated.		
	Changes in "	General description", "Features	and benefits" and "	Applications".
HEF4069UB v.7	20110511	Product data sheet	-	HEF4069UB v.6
HEF4069UB v.6	20091208	Product data sheet	-	HEF4069UB v.5
HEF4069UB v.5	20090723	Product data sheet	-	HEF4069UB v.4
HEF4069UB v.4	20080704	Product data sheet	-	HEF4069UB_CNV v.3
HEF4069UB_CNV v.3	19950101	Product specification	-	HEF4069UB_CNV v.2
HEF4069UB_CNV v.2	19950101	Product specification	-	-

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Document status[1][2]	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Hex unbuffered inverter

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HEF4069UB

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